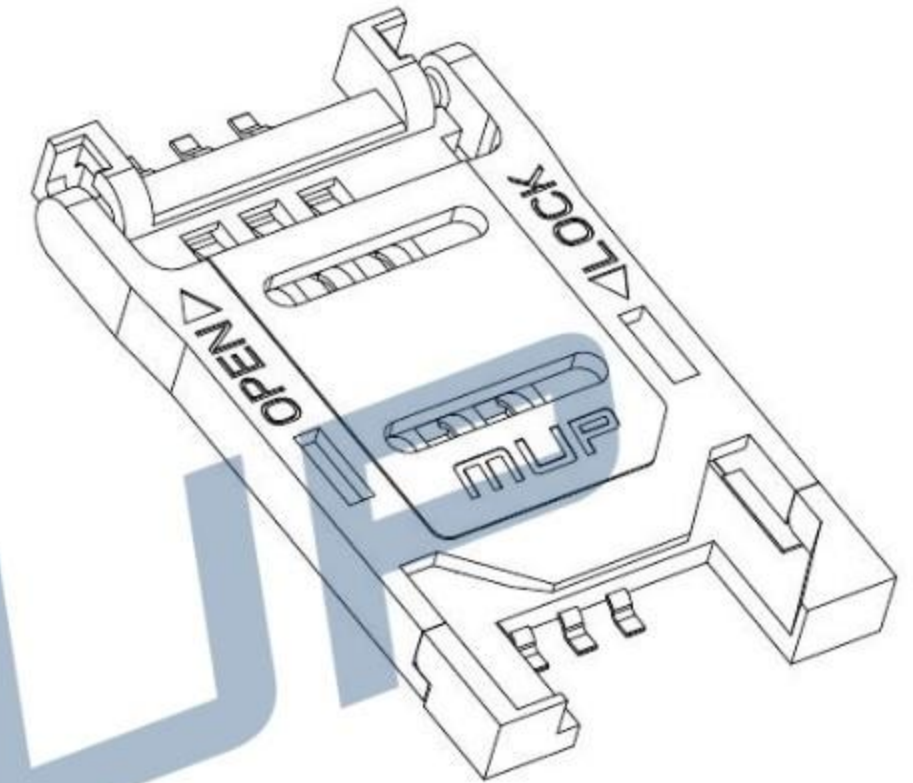
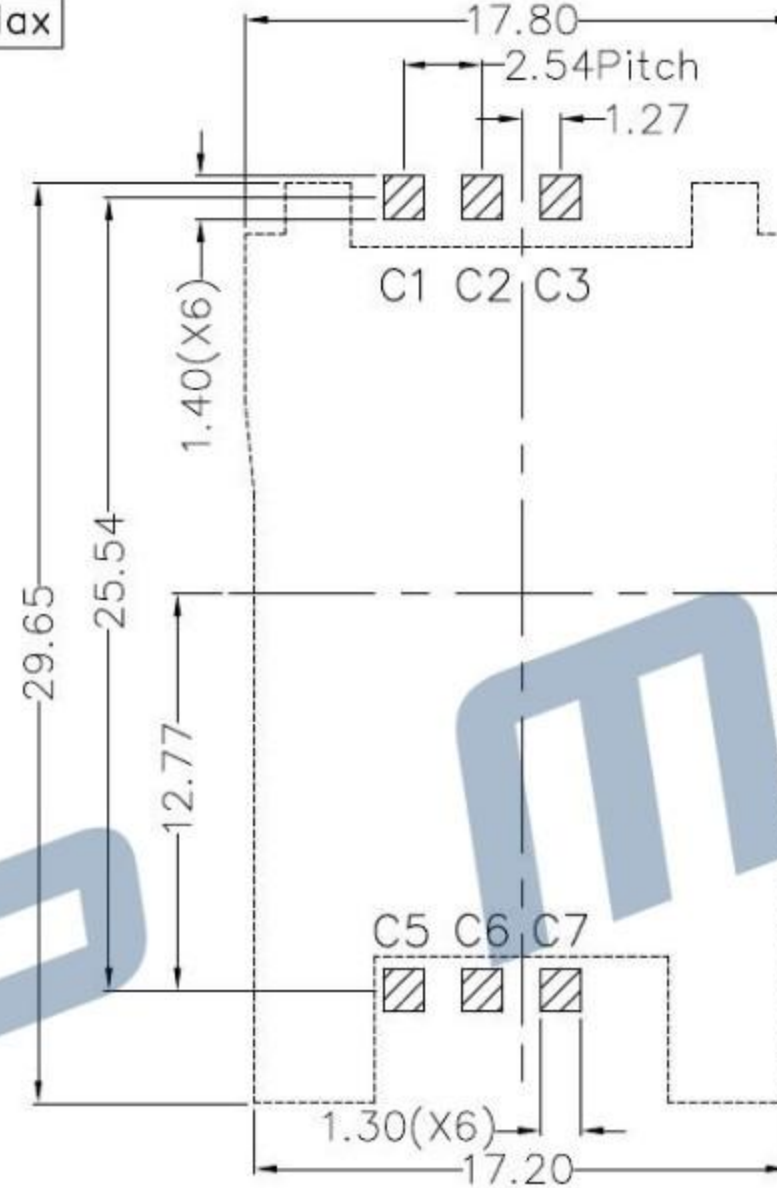
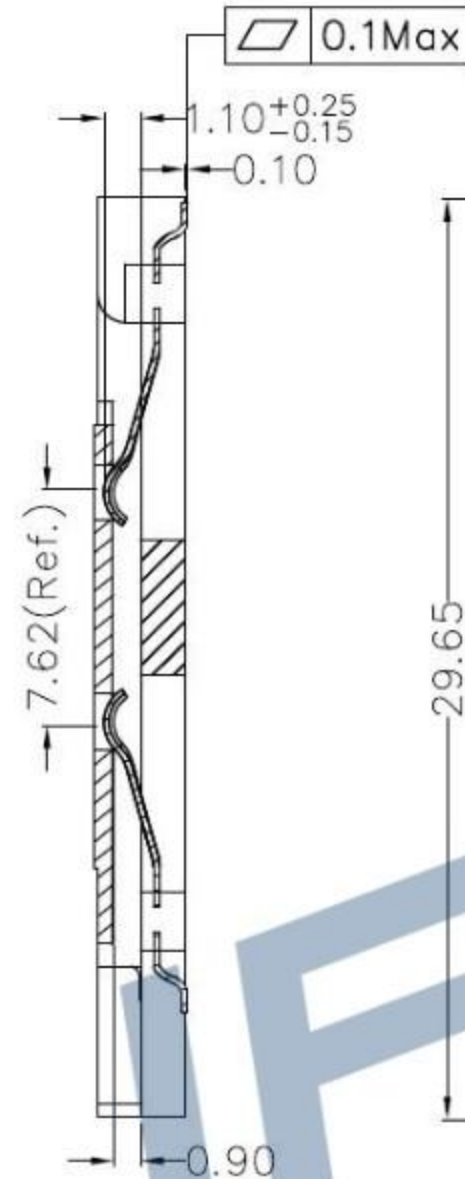
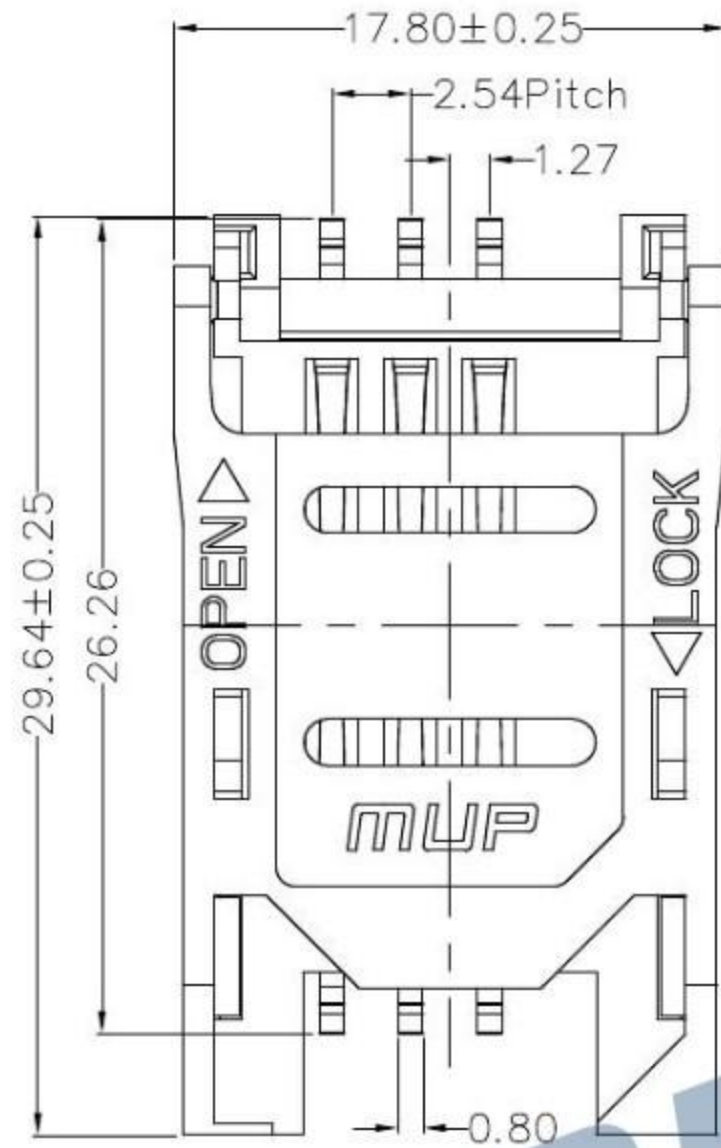


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 29.65LX17.80WX2.80H mm

Weight: Approx1.14±0.20g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec. Max

IR reflow: 250°C, 5sec. Max

Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH

RECOMMENDED P.C.B LAYOUT COMPONENT SIDE(TOLERANCE ±0.05)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Black UL94V-0
3	DATA CONTACT	6	Copper Alloy	Contact area: 5u" Au plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

PROJ.	UNIT	SCALE
①	mm	1:1

CUSTOMER DRAWING

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C713-27**

TYPE: **H2.8 without post 6p**

DRAWN: Zoey Mar.10.2006 DWG NO.: DWG-MUP-C713-027

CHECKED: Jimmy Mar.10.2006 SHEET: 1/1 REVISION: X1

APPROVAL: Jun Mar.10.2006

